# HIGH-SPEED 3.3V 16/8K X 9 SYNCHRONOUS PIPELINED DUAL-PORT STATIC RAM

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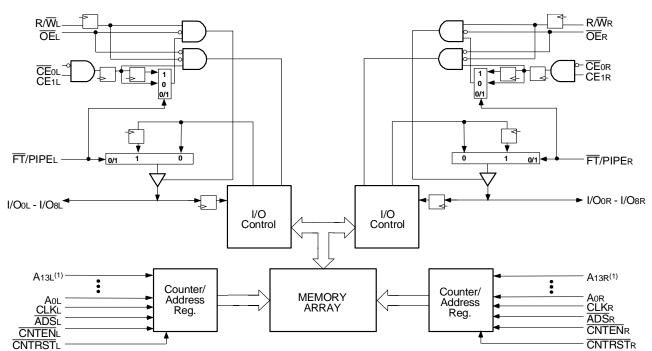
# Features:

- True Dual-Ported memory cells which allow simultaneous access of the same memory location
- High-speed clock to data access
  - Commercial: 6.5/7.5/9ns (max.)
- Industrial: 7.5ns (max.)
- Low-power operation
  - IDT70V916/59L/59L
    Active: 450mW (typ.)
    Standby: 1.5mW (typ.)
- Flow-Through or Pipelined output mode on either port via the FT/PIPE pins
- Counter enable and reset features

Functional Block Diagram

 Dual chip enables allow for depth expansion without additional logic

- Full synchronous operation on both ports
- 3.5ns setup to clock and Ons hold on all control, data, and address inputs
- Data input, address, and control registers
- Fast 6.5ns clock to data out in the Pipelined output mode
- Self-timed write allows fast cycle time
- 10ns cycle time, 100MHz operation in Pipelined output mode
- Separate upper-byte and lower-byte controls for multiplexed bus and bus matching compatibility
- LVTTL- compatible, single 3.3V (±0.3V) power supply
- Industrial temperature range (-40°C to +85°C) is available for 83 MHz
- Available in a 100-pin Thin Quad Flatpack (TQFP) and 100pin fine pitch Ball Grid Array (fpBGA) packages.



5655 drw 01

### NOTE:

1. A<sub>13</sub> is a NC for IDT70V9159.

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### IDT70V9169/59L

High-Speed 3.3V 16/8K x 9 Dual-Port Synchronous Pipelined Static RAM

Industrial and Commercial Temperature Ranges

### Description:

The IDT70V9169/59 is a high-speed 16/8K x 9 bit synchronous Dual-Port RAM. The memory array utilizes Dual-Port memory cells to allow simultaneous access of any address from both ports. Registers on control, data, and address inputs provide minimal setup and hold times. The timing latitude provided by this approach allows systems to be designed with very short cycle times. With an input data register, the IDT70V9169/59 has been optimized for applications having unidirectional or bidirectional data flow in bursts. An automatic power down feature, controlled by  $\overline{CE}_0$  and CE1, permits the on-chip circuitry of each port to enter a very low standby power mode. Fabricated using IDT's CMOS high-performance technology, these devices typically operate on only 450mW of power.

#### PinConfigurations<sup>(1,2,3,4)</sup> 06/21/02 Index A1R Agr AGL АЗL A5I 44 100 99 98 97 96 95 94 93 92 91 90 89 88 87 86 85 84 83 82 81 80 79 78 77 76 75 NC ⊐ NC NC □ ⊐ NC 2 74 A7L C ⊐ A7R 73 ⊐ A8R A8L 72 ⊐ A9r A9L □ 71 5 <sup>–</sup> A10R A10L 70 □ A11R A11L □ 69 A12L 8 68 ⊐ A12R A13L<sup>(1)</sup> ⊐ A13R<sup>(1)</sup> 9 67 70V9169/59PF ⊐ NC NC 10 66 PN100-1<sup>(5)</sup> <sup>⊐</sup> NC 111 65 12 64 <sup>D</sup> NC 100-Pin TQFP 63 ⊐ Vss Top View<sup>(6)</sup> NC 14 ⊐ NC 62 NC □15 <sup>⊐</sup> NC 61 NC 16 60 ⊐ NC NC 17 59 ⊐ NC □ CEOR 58 □ CE1R CE1I □ 19 57 CNTRSTR CNTRSTL □ 20 56 55 ⊐ R/WR 54 □ FT/PIPER 53 52 ⊐ Vss 24 NC ⊏ ⊐ NC 25 51 50 U 5655 drw 02 Ŝ ÿ

- 1. A13 is a NC for IDT70V9159.
- 2. All VDD pins must be connected to power supply.
- 3. All Vss pins must be connected to ground supply.
- 4. Package body is approximately 14mm x 14mm x 1.4mm.
- 5. This package code is used to reference the package diagram.
- 6. This text does not indicate orientation of the actual part-marking.

# PinConfigurations(cont'd)<sup>(1,2,3,4)</sup>

## 70V9169/59PF BF100<sup>(5)</sup>

## 100-Pin fpBGA Top View<sup>(6)</sup>

06/21/02

A1	a2	A3	A4	<sup>A5</sup>	A6	A7	<sup>A8</sup>	<sup>A9</sup>	A10
A6R	A9r	A12R	NC	Vss	Vss	NC	R/WR	Vss	NC
B1	b2	B3	B4	B5	B6	B7	B8	<sup>B9</sup>	b10
A4R	A5r	A8R	A10R	NC	NC	NC	OEr	NC	I/O6R
С1	C2	C3	C4	<sup>C5</sup>	C6		C8	C9	С10
Азк	NC	NC	A7R	NC	CE0R		PL/FTR	I/O7R	I/ <b>О</b> 3R
D1	D2	D3	D4	d5		D7	d8	d9	d10
Aor	CLKR	A1R	A2R	A11r		CNTRST <sub>R</sub>	I/O8r	I/O5r	I/O1r
E1	e2	E3	E4	E5	E6	e7	e8	e9	e10
Vss	ADSr	<u>CNTEN</u> r	A1L	ADSL	Vss	I/O4r	I/O2r	I/Oor	Vdd
F1	F2	F3	F4	f5	<sup>F6</sup>	f7	F8	F9	F10
Vss	CLKL	Aol	A3L	Vdd	Vss	Vdd	I/O2l	I/O1L	I/Ool
G1	G2	G3	G4	G5	G6	G7	G8	<sup>G9</sup>	G10
CNTEN⊾	NC	A5L	A12L	NC	R∕₩L	NC	I/O4L	Vss	I/ОзL
H1	H2	нз	H4	H5	H6	H7	H8	H9	h10
A2L	A4L	Аэ∟	A13L <sup>(1)</sup>	NC	CE1L	NC	I/O7∟	I/O6L	I/O5l
J1	J2	J3	J4	J5	J6	J7	<sub>J8</sub>	<sub>J9</sub>	J10
NC	A7L	A10∟	NC	NC	NC	OEL	Vss	Vss	I∕O8L
к1	к2	кз	к4	к5	k6		K8	k9	к10
АбL	A8L	A11L	NC	Vdd	Vdd		CNTRST∟	PL∕FT∟	NC

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- 1. A13 is a NC for IDT70V9159.
- 2. All VDD pins must be connected to power supply.
- 3. All Vss pins must be connected to ground supply.
- 4. Package body is approximately 10mm x 10mm x 1.4mm with 0.8mm ball pitch.
- 5. This package code is used to reference the package diagram.
- 6. This text does not indicate orientation of the actual part-marking.

# **Pin Names**

Left Port	Right Port	Names
CEOL, CE1L	$\overline{CE}$ OR, CE1R	Chip Enables
R/WL	R/Wr	Read/Write Enable
ŌĒL	<del>0E</del> r	Output Enable
Aol - A13l <sup>(1)</sup>	Aor - A13r <sup>(1)</sup>	Address
1/Ool - 1/O8l	1/Oor - 1/O8r	Data Input/Output
CLKL	CLKr	Clock
ADSL	<b>ADS</b> R	Address Strobe
		Counter Enable
		Counter Reset
FT/PIPEL	<b>FT</b> /PIPER	Flow-Through/Pipeline
V	DD	Power (3.3V)
V	SS	Ground (0V)

NOTE:

5655 tbl 01

1. A13 is a NC for IDT70V9159.

# Truth Table I—Read/Write and Enable Control<sup>(1,2,3)</sup>

ŌĒ	CLK	<b>CE</b> ₀	CE1	R/W	I/O0-8	Mode
Х	$\uparrow$	Н	Х	Х	High-Z	Deselected—Power Down
Х	Ŷ	Х	L	Х	High-Z	Deselected—Power Down
Х	$\uparrow$	L	Н	L	DATAIN	Write
L	Ŷ	L	Н	Н	DATAOUT	Read
Н	Х	L	Н	Х	High-Z	Outputs Disabled

NOTES:

1. "H" = VIH, "L" = VIL, "X" = Don't Care.

2.  $\overline{ADS}$ ,  $\overline{CNTEN}$ ,  $\overline{CNTRST} = X$ .

3.  $\overline{\mathsf{OE}}$  is an asynchronous input signal.

#### IDT70V9169/59L High-Speed 3.3V 16/8K x 9 Dual-Port Synchronous Pipelined Static RAM

Industrial and Commercial Temperature Ranges

5655 tbl 03

5655 tbl 05

5655 tbl 07

# Truth Table II—Address Counter Control<sup>(1,2)</sup>

External Address	Previous Internal Address	Internal Address Used	CLK	ADS	CNTEN	CNTRST	I/O <sup>(3)</sup>	MODE
An	Х	An	Ŷ	L <sup>(4)</sup>	Х	Н	Dvo (n)	External Address Used
Х	An	An + 1	Ŷ	Н	L <sup>(5)</sup>	Н	Dvo(n+1)	Counter Enabled—Internal Address generation
Х	An + 1	An + 1	Ŷ	Н	Н	Н	Dvo(n+1)	External Address Blocked—Counter disabled (An + 1 reused)
Х	Х	Ao	$\uparrow$	Х	Х	L <sup>(4)</sup>	Dvo(0)	Counter Reset to Address 0

### NOTES:

1.  $\underline{H}^{"} = \underline{V_{IH}, \underline{L}^{"}} = V_{IL, \underline{X}^{"}} = Don't Care.$ 

2.  $\overline{CE}_{0}$ ,  $\overline{LB}$ ,  $\overline{UB}$ , and  $\overline{OE}$  = VIL; CE1 and R/W = VIH.

3. Outputs configured in Flow-Through Output mode: if outputs are in Pipelined mode the data out will be delayed by one cycle.

4. ADS and CNTRST are independent of all other signals including CEo, CE1, UB and LB.

5. The address counter advances if CNTEN = VIL on the rising edge of CLK, regardless of all other signals including CEo, CE1, UB and LB.

# Recommended Operating Temperature and Supply Voltage

Grade	Ambient Temperature <sup>(1)</sup>	GND	Vdd
Commercial	0°C to +70°C	0V	3.3V <u>+</u> 0.3V
Industrial	-40°C to +85°C	0V	3.3V <u>+</u> 0.3V
			5655 tbl 04

NOTES:

1. This is the parameter TA. This is the "instant on" case temperature.

# Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Мах.	Unit
Vdd	Supply Voltage	3.0	3.3	3.6	V
Vss	Ground	0	0	0	V
Vih	Input High Voltage	2.0		VDD+0.3V <sup>(2)</sup>	V
VIL	Input Low Voltage	-0.3(1)	_	0.8	V

NOTES:

1. VIL  $\geq$  -1.5V for pulse width less than 10 ns.

2. VTERM must not exceed VDD+0.3V.

# Absolute Maximum Ratings<sup>(1)</sup>

Symbol	Rating	Commercial & Industrial	Unit
Vterm <sup>(2)</sup>	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
Tbias	Temperature Under Bias	-55 to +125	٥C
Tstg	Storage Temperature	-65 to +150	٥C
Ιουτ	DC Output Current	50	mA
NOTES.			5655 tbl 06

NOTES:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2. VTERM must not exceed Vbb +0.3V for more than 25% of the cycle time or 10ns maximum, and is limited to  $\leq$  20mA for the period of VTERM  $\geq$  Vbb + 0.3V.

# Capacitance<sup>(1)</sup> (TA = $+25^{\circ}$ C, f = 1.0MHz)

Symbol	Parameter	Conditions <sup>(2)</sup>	Мах.	Unit
CĩN	Input Capacitance	Vin = 3dV	9	pF
Cout <sup>(3)</sup>	Output Capacitance	Vout = 3dV	10	pF

NOTES:

1. These parameters are determined by device characterization, but are not production tested.

2. 3dV references the interpolated capacitance when the input and output switch from 0V to 3V or from 3V to 0V.

3. COUT also references CI/O.

Industrial and Commercial Temperature Ranges

# DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range ( $V_{DD}$ = 3.3V ± 0.3V)

			70V91	69/59L	
Symbol	Parameter	Test Conditions	Min.	Max.	Unit
Lu	Input Leakage Current <sup>(1)</sup>	$V_{DD}$ = 3.6V, $V_{IN}$ = 0V to $V_{DD}$	_	5	μA
Ilo	Output Leakage Current	$\overline{CE}$ = VIH or CE1 = VIL, VOUT = 0V to VDD		5	μA
Vol	Output Low Voltage	IoL = +4mA		0.4	V
Vон	Output High Voltage	IOH = -4mA	2.4	I	V

NOTE:

1. At  $V_{DD} \leq 2.0V$  input leakages are undefined.

# DC Electrical Characteristics Over the Operating Temperature Supply Voltage Range<sup>(3)</sup> ( $V_{DD} = 3.3V \pm 0.3V$ )

						69/59L6 I Only		59/59L7 & Ind		69/59L9 I Only	
Symbol	Parameter	Test Condition	Versio	n	Тур. <sup>(4)</sup>	Мах.	Тур. <sup>(4)</sup>	Max.	Тур. <sup>(4)</sup>	Мах.	Unit
ldd	Dynamic Operating	$\overline{CE}_{L}$ and $\overline{CE}_{R=}$ VL,	COM'L	L	175	330	155	280	135	230	mA
	Current (Both Ports Active)	Outputs Disabled, $f = fMAX^{(1)}$	IND	L			155	330			
ISB1	Standby Current	$\overline{C}\overline{E}L = \overline{C}\overline{E}R = VIH$	COM'L	L	50	80	40	70	30	60	mA
	(Both Ports - TTL Level Inputs)	$f = fMAX^{(1)}$	IND	L		-	40	80			
ISB2	Standby	<u>CE</u> "A" = VL and	COM'L	L	115	185	105	170	95	155	mA
	Current (One Port - TTL Level Inputs)	$\overline{C}\overline{E}^{"}B" = VIH^{(5)}$ Active Port Outputs Disabled, f=fMAX <sup>(1)</sup>	IND	L			105	180			
ISB3	Full Standby	Both Ports CEL and	COM'L	L	0.5	3.0	0.5	3.0	0.5	3.0	mA
	Current (Both Ports - CMOS Level Inputs)	$\label{eq:certain} \begin{split} \overline{C} \overline{E} R \ge & V_{DD} - 0.2V, \\ V_{IN} \ge & V_{DD} - 0.2V \text{ or} \\ V_{IN} \le & 0.2V, \ f = & 0^{(2)} \end{split}$	IND	L			0.5	3.0			
ISB4	Full Standby	$\overline{CE}$ "A" $\leq 0.2V$ and	COM'L	L	105	175	95	160	85	145	mA
	Current (One Port - CMOS Level Inputs)	$\begin{array}{l} \overline{C}\overline{E}"B" \ \geq \ V_{DD} - 0.2V^{(5)} \\ \overline{V} N \ \geq \ V_{DD} - 0.2V \ or \\ \overline{V} N \ \leq \ 0.2V, \ Active \ Port, \\ Outputs \ Disabled \ , \ f \ = \ fmAx^{(1)} \end{array}$	IND	L			95	175			

NOTES:

- 1. At f = fMAX, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcyc, using "AC TEST CONDITIONS" at input levels of GND to 3V.
- 2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.
- 3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".
- 4.  $V_{DD}$  = 3.3V, TA = 25°C for Typ, and are not production tested. Icc pc(f=0) = 90mA (Typ).
- 5.  $\overline{CE}x = VIL$  means  $\overline{CE}ox = VIL$  and CE1x = VIH
- $\overline{CE}x = VIH$  means  $\overline{CE}_{0X} = VIH$  or  $CE_{1X} = VIL$
- $\overline{CE}x \le 0.2V$  means  $\overline{CE}ox \le 0.2V$  and  $CE_{1X} \ge V_{DD} 0.2V$
- $\overline{CE}x \geq ~V\text{dd}$  0.2V means  $\overline{CE}\text{dx} \geq ~V\text{dd}$  0.2V or CE1x  $\leq 0.2V$
- "X" represents "L" for left port or "R" for right port.

5655 tbl 08

5655 tbl 09

# IDT70V9169/59L

High-Speed 3.3V 16/8K x 9 Dual-Port Synchronous Pipelined Static RAM

Industrial and Commercial Temperature Ranges

# AC Test Conditions

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	2ns Max.
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	Figures 1, 2 & 3

5655 tbl 10

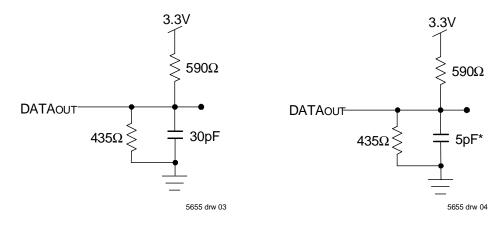


Figure 1. AC Output Test load.

Figure 2. Output Test Load (For tcklz, tckHz, tolz, and toHz). \*Including scope and jig.

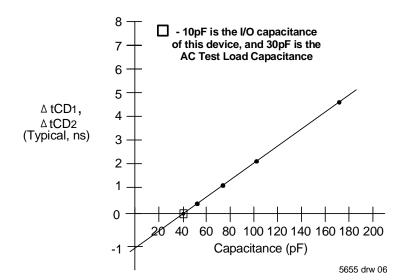


Figure 3. Typical Output Derating (Lumped Capacitive Load).

High-Speed 3.3V 16/8K x 9 Dual-Port Synchronous Pipelined Static RAM

Industrial and Commercial Temperature Ranges

# AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing)<sup>(3)</sup> ( $V_{DD}$ = 3.3V ± 0.3V, TA = 0°C to +70°C)

		70V91 Com'	69/59L6 I Only	70V91 Com'l	69/59L7 & Ind	59L7 70V9169/59L9 Ind Com'l Only		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
tcyc1	Clock Cycle Time (Flow-Through) <sup>(2)</sup>	19	_	22	_	25	—	ns
tcyc2	Clock Cycle Time (Pipelined) <sup>(2)</sup>	10	_	12	_	15	—	ns
tCH1	Clock High Time (Flow-Through) <sup>(2)</sup>	6.5		7.5		12	—	ns
tCL1	Clock Low Time (Flow-Through) <sup>(2)</sup>	6.5		7.5		12	—	ns
tcн2	Clock High Time (Pipelined) <sup>(2)</sup>	4		5		6	—	ns
tCL2	Clock Low Time (Pipelined) <sup>(2)</sup>	4		5		6	—	ns
tR	Clock Rise Time		3		3	—	3	ns
tr	Clock Fall Time		3		3	—	3	ns
tsa	Address Setup Time	3.5		4		4	—	ns
tha	Address Hold Time	0		0		1	—	ns
tsc	Chip Enable Setup Time	3.5		4		4	—	ns
tнc	Chip Enable Hold Time	0		0	-	1	—	ns
tsв	Byte Enable Setup Time	3.5		4		4	—	ns
tнв	Byte Enable Hold Time	0		0		1	—	ns
tsw	R/W Setup Time	3.5		4	_	4	—	ns
tHW	R/W Hold Time	0		0		1	—	ns
tsp	Input Data Setup Time	3.5	_	4	_	4	—	ns
thd	Input Data Hold Time	0		0		1	_	ns
tsad	ADS Setup Time	3.5		4	_	4	_	ns
thad	ADS Hold Time	0	—	0		1	-	ns
tscn	CNTEN Setup Time	3.5	_	4		4	_	ns
then	CNTEN Hold Time	0		0		1	—	ns
<b>t</b> SRST	CNTRST Setup Time	3.5		4		4	—	ns
thrst	CNTRST Hold Time	0		0		1		ns
toe	Output Enable to Data Valid		6.5		7.5	—	9	ns
tolz	Output Enable to Output Low-Z <sup>(1)</sup>	2		2		2		ns
tонz	Output Enable to Output High-Z <sup>(1)</sup>	1	7	1	7	1	7	ns
tCD1	Clock to Data Valid (Flow-Through) <sup>(2)</sup>		15		18	—	20	ns
tCD2	Clock to Data Valid (Pipelined) <sup>(2)</sup>		6.5		7.5	—	9	ns
tDC	Data Output Hold After Clock High	2		2		2	—	ns
tскнz	Clock High to Output High-Z <sup>(1)</sup>	2	9	2	9	2	9	ns
tCKLZ	Clock High to Output Low-Z <sup>(1)</sup>	2		2		2	—	ns
Port-to-Port	Delay	<b>_</b>						
tcwdd	Write Port Clock High to Read Data Delay		24		28		35	ns
tccs	Clock-to-Clock Setup Time		9		10		15	ns

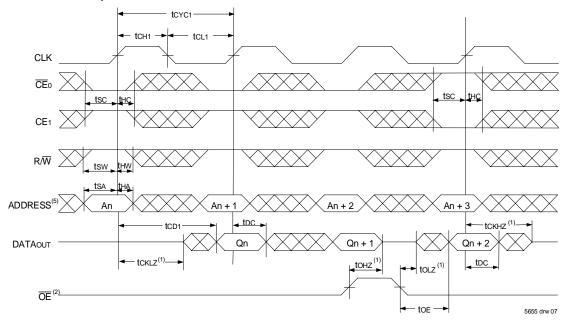
1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2). This parameter is guaranteed by device characterization, but is not production tested.

2. The Pipelined output parameters (tcvc2, tcb2) apply to either or both the Left and Right ports when FT/PIPE = VIH. Flow-through parameters (tcvc1, tcb1) apply when FT/PIPE = VIL for that port.

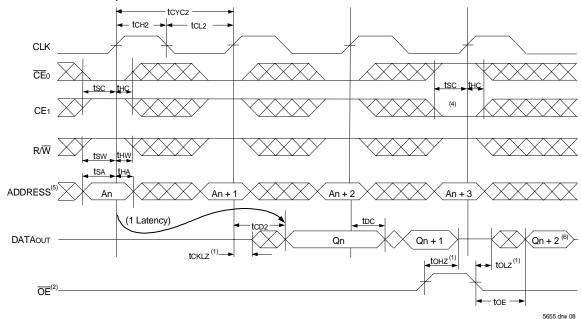
3. All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (OE), FT/PIPER, and FT/PIPEL.

High-Speed 3.3V 16/8K x 9 Dual-Port Synchronous Pipelined Static RAM

Timing Waveform of Read Cycle for Flow-Through Output  $(FT/PIPE"x" = VIL)^{(3,6)}$ 



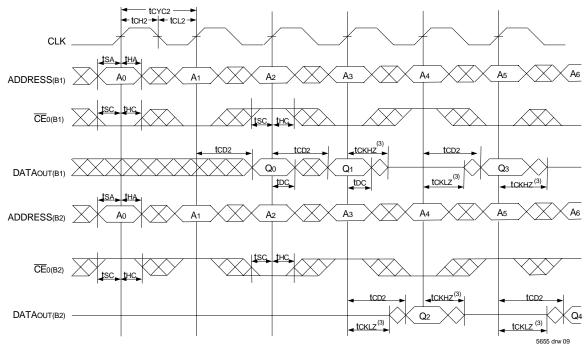
Timing Waveform of Read Cycle for Pipelined Operation  $(FT/PIPE"x" = VIH)^{(3,6)}$ 



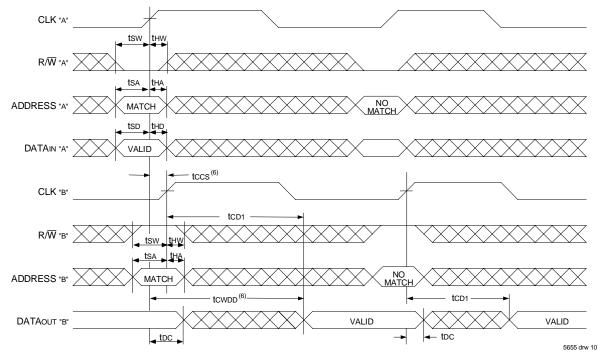
- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. OE is asynchronously controlled; all other inputs are synchronous to the rising clock edge.
- 3. ADS = VIL, CNTEN and CNTRST = VIH.
- 4. The output is disabled (High-Impedance state) by  $\overline{CE}_0 = V_{IH}$ ,  $CE_1 = V_{IL}$  following the next rising edge of the clock. Refer to Truth Table 1.
- 5. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers
- are for reference use only. 6. "X' here denotes Left or Right port. The diagram is with respect to that port.

Industrial and Commercial Temperature Ranges

Timing Waveform of a Bank Select Pipelined Read<sup>(1,2)</sup>

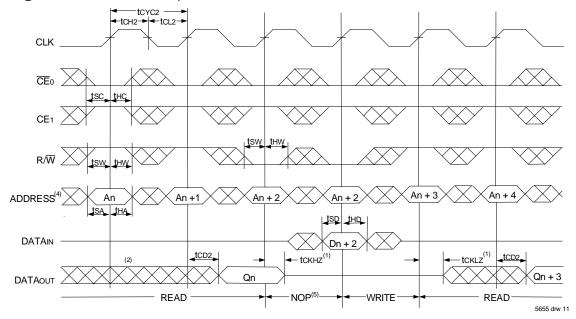


Timing Waveform with Port-to-Port Flow-Through Read<sup>(4,5,7)</sup>

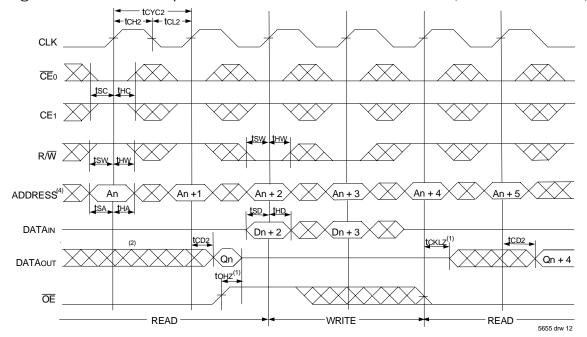


- 1. B1 Represents Bank #1; B2 Represents Bank #2. Each Bank consists of one IDT70V916/59L for this waveform, and are setup for depth expansion in this example. ADDRESS(B1) = ADDRESS(B2) in this situation.
- 2.  $\overline{OE}$  and  $\overline{ADS}$  = VIL;  $\overline{CE1(B1)}$ ,  $\overline{CE1(B2)}$ ,  $\overline{R/W}$ ,  $\overline{CNTEN}$ , and  $\overline{CNTRST}$  = VIH.
- 3. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 4.  $\overline{CE}_0$  and  $\overline{ADS} = VIL$ ; CE1,  $\overline{CNTEN}$ , and  $\overline{CNTRST} = VIH$ .
- 5.  $\overline{OE} = V_{IL}$  for the Right Port, which is being read from.  $\overline{OE} = V_{IH}$  for the Left Port, which is being written to.
- 6. If tccs ≤ maximum specified, then data from right port READ is not valid until the maximum specified for tcwpp.
- If tccs > maximum specified, then data from right port READ is not valid until tccs + tcp1. tcwpp does not apply in this case.
- 7. All timing is the same for both Left and Right ports. Port "A" may be either Left or Right port. Port "B" is the opposite from Port "A".

Timing Waveform of Pipelined Read-to-Write-to-Read ( $\overline{OE} = VIL$ )<sup>(3)</sup>

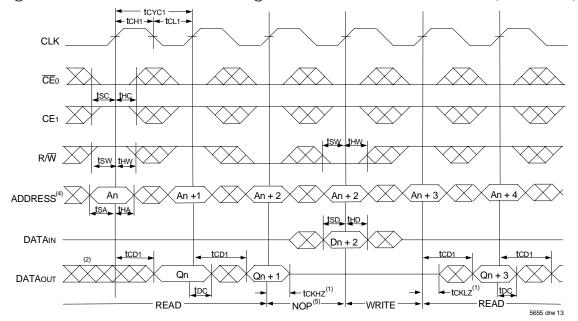


Timing Waveform of Pipelined Read-to-Write-to-Read (**OE** Controlled)<sup>(3)</sup>

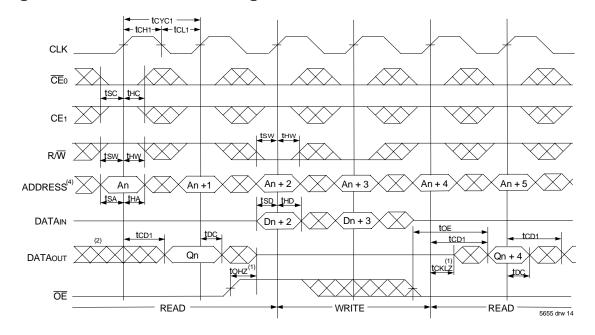


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 3. CEo and ADS = VIL; CE1, CNTEN, and CNTRST = VIH. "NOP" is "No Operation".
- 4. Addresses do not have to be accessed sequentially since ADS = ViL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.

Timing Waveform of Flow-Through Read-to-Write-to-Read ( $\overline{OE} = VIL$ )<sup>(3)</sup>

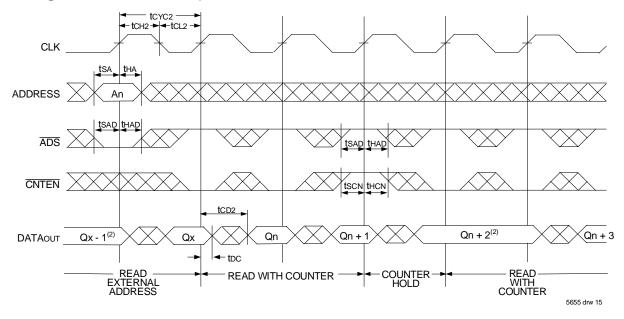


Timing Waveform of Flow-Through Read-to-Write-to-Read (**OE** Controlled)<sup>(3)</sup>

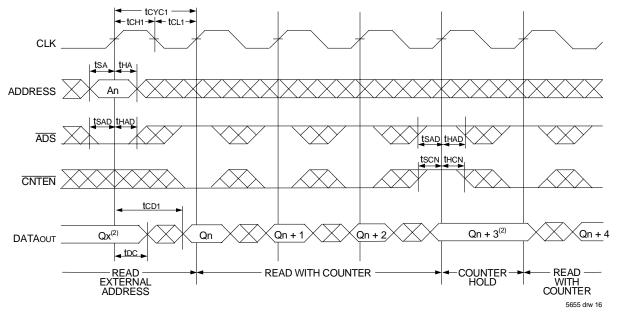


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
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- 3. CEo and ADS = VIL; CE1, CNTEN, and CNTRST = VIH. "NOP" is "No Operation".
- 4. Addresses do not have to be accessed sequentially since ADS = ViL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.

Timing Waveform of Pipelined Read with Address Counter Advance<sup>(1)</sup>



Timing Waveform of Flow-Through Read with Address Counter Advance<sup>(1)</sup>

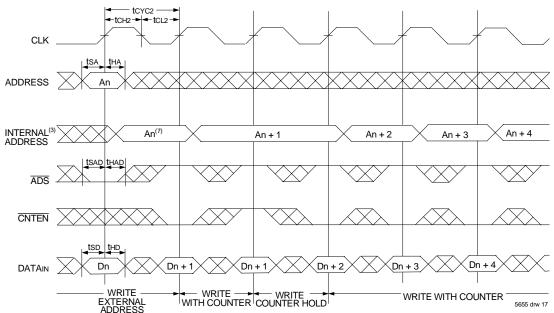


### NOTES:

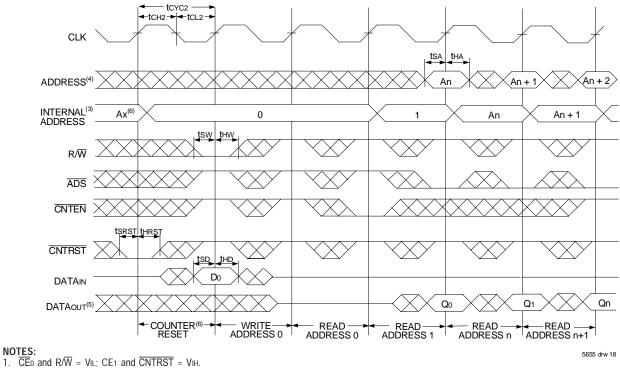
1.  $\overline{CE}_0$  and  $\overline{OE} = V_{IL}$ ; CE1, R/W, and  $\overline{CNTRST} = V_{IH}$ .

2. If there is no address change via ADS = VIL (loading a new address) or CNTEN = VIL (advancing the address), i.e. ADS = VIH and CNTEN = VIH, then the data output remains constant for subsequent clocks.

# Timing Waveform of Write with Address Counter Advance (Flow-Through or Pipelined Outputs)<sup>(1)</sup>



Timing Waveform of Counter Reset (Pipelined Outputs)<sup>(2)</sup>



- 2.  $\overline{CE}_0 = VIL; CE_1 = VIH.$
- 3. The "Internal Address" is equal to the "External Address" when ADS = VIL and equals the counter output when ADS = VIH.
- 4. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- No dead cycle exists during counter reset. A READ or WRITE cycle may be coincidental with the counter reset cycle. ADDRo will be accessed. Extra cycles 6. are shown here simply for clarification.
- 7. CNTEN = VIL advances Internal Address from 'An' to 'An +1'. The transition shown indicates the time required for the counter to advance. The 'An +1' Address is written to during this cycle.

### IDT70V9169/59L

High-Speed 3.3V 16/8K x 9 Dual-Port Synchronous Pipelined Static RAM

# Functional Description

The IDT70V9169/59 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide minimal set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal, however, the self-timed internal write pulse is independent of the LOW to HIGH transition of the clock signal.

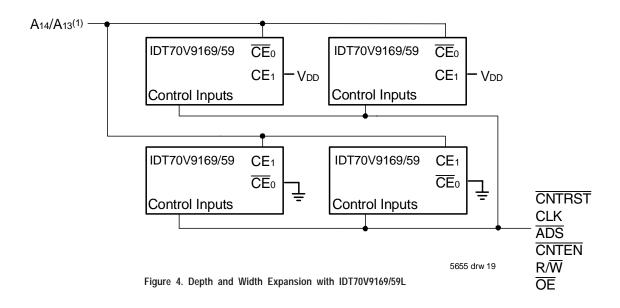
An asynchronous output enable is provided to ease asynchronous bus interfacing. Counter enable inputs are also provided to stall the operation of the address counters for fast interleaved memory applications.

 $\overline{CE}_0 = VIL$  and  $CE_1 = VIH$  for one clock cycle will power down the internal circuitry to reduce static power consumption. Multiple chip enables allow easier banking of multiple IDT70V9169/59's for depth expansion configurations. When the Pipelined output mode is enabled, two cycles are required with  $\overline{CE}_0 = VIL$  and  $CE_1 = VIH$  to re-activate the outputs.

# Depth and Width Expansion

The IDT70V9169/59 features dual chip enables (refer to Truth Table I) in order to facilitate rapid and simple depth expansion with no requirements for external logic. Figure 4 illustrates how to control the varioius chip enables in order to expand two devices in depth.

The IDT70V9169/59 can also be used in applications requiring expanded width, as indicated in Figure 4. Since the banks are allocated at the discretion of the user, the external controller can be set up to drive the input signals for the various devices as required to allow for 36-bit or wider applications.



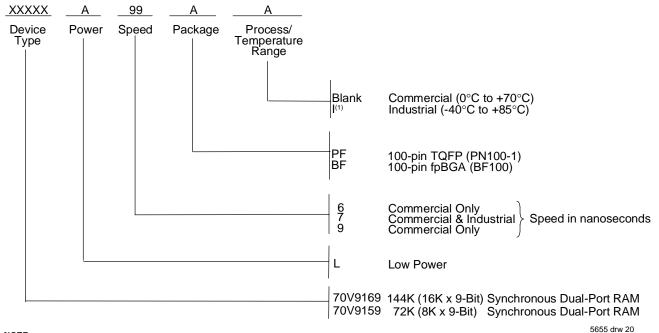
### NOTE:

1. A14 is for IDT70V9169, A13 is for IDT70V9159.

### IDT70V9169/59L

High-Speed 3.3V 16/8K x 9 Dual-Port Synchronous Pipelined Static RAM

# Ordering Information



NOTE:

1. Contact your local sales office for Industrial temp range for other speeds, packages and powers.

# IDT Clock Solution for IDT70V9169/59 Dual-Port

IDT Dual-Port Part Number	Dual-Port I/O Specitications		Clock Specifications				IDT	IDT
	Voltage	I/O	Input Capacitance	Input Duty Cycle Requirement	Maximum Frequency	Jitter Tolerance	PLL Clock Device	Non-PLL Clock Device
70V9169/59	3.3	LVTTL	9pF	40%	100	150ps	IDT2305 IDT2308 IDT2309	FCT3805 FCT3805D/E FCT3807 FCT3807D/E

5638 tbl 12

# Datasheet Document History

- 07/08/02: Initial Public Release
- 08/15/03: Removed Preliminary status
- Page 16 Added IDT Clock Solution Table
- 01/29/09: Page 16 Removed "IDT" from orderable part number



**CORPORATE HEADQUARTERS** 6024 Silver Creek Valley Road San Jose, CA 95138 *for SALES:* 800-345-7015 or 408-284-8200 fax: 408-284-2775 www.idt.com *for Tech Support:* 408-284-2794 DualPortHelp@idt.com

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